







(1.50 mm) .059" X (1.75 mm) .069"

TPAF SERIES

EED ELEVATED ARRAY RECEPTA

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?TPAF

Insulator Material:

Black LCP (TPAF-M) Gray LCP (TPAF-D) Contact Material:

Copper Alloy **Ground Plane:**

Copper Alloy
Operating Temp Range:
-55 °C to +125 °C

Plating: Au or Sn over 50 µ" (1.27 µm) Ni Working Voltage: 165 VAC / 230 VAC **RoHS Compliant:**

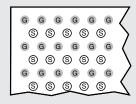
Lead-Free Solderable:

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

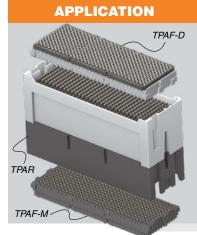


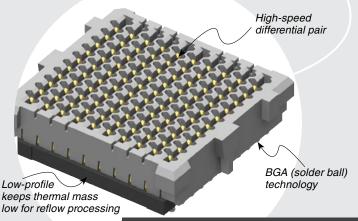
SIGNAL MAPPING



For complete signal mapping, see www.samtec.com?TPAF

Mates with:





HIGH-SPEED CHANNEL PERFORMANCE

TPAF/TPAR @ 35 mm Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com



= Mounting

TPAF



MOD 1



only)

MOD 2

= High-speed Differential Pair (Leave blank for module 1 or 2 only

MOD 3

= 30 µ" (0.76 µm) Gold on contact area Matte Tin on solder tail

PLATING

OPTION

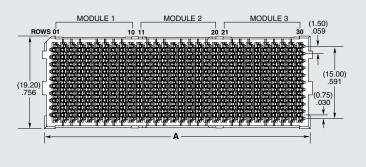


SOLDER

TYPE



OPTION



| ı | MODULES | PAIRS | Α |
|---|---------|-------|------------------|
| | 1 | 50 | (21.00) .827 |
| | 2 | 100 | (38.50) 1.516 |
| | 3 | 150 | (56.00) 2.205 |

Entire system requires TPAF-D, TPAF-M and TPAR.

Tape & Reel packaging is standard.

Dual source for Hirose IT5. Some sizes, styles and options are non-standard, non-returnable.







TPAR SERIES

(1.50 mm) .059" X (1.75 mm) .069"

HIGH-SPEED ELEVATED ARRAY RISER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?TPAR

Insulator Material:

Contact Material: Copper Alloy Operating Temp Range: 55 °C to +125 °C

Plating:

Au over 50 μ" (1.27 μm) Ni Working Voltage: 165 VAC / 230 VAC

RoHS Compliant:

Lead-Free Solderable:

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

• 18 to 40 mm mated heights

TOOLING · Installation Cap: CAT-PT-TPAR-X Removal Tool: CAT-EX-TPAR-X

Notes:

Entire system requires TPAF-D, TPAF-M and TPAR.

Tray is standard packaging

Dual source for Hirose IT5.

Some sizes, styles and options are non-standard, non-returnable.

Mates with:

TPAF-D, TPAF-M

WAFER DESIGN Cutaway shown for clarity Polarity-swapping technology greatly reduces crosstalk in 100 Ω , differential applications.

Elevated stack heights allow better system air flow 35 mm standard mated height achieved when mated with TPAF-M and TPAF-D HIGH-SPEED CHANNEL PERFORMANCE TPAF/TPAR @ 35 mm Stack Height Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

TPAR **MODULE 1 MODULE 2**

-H

= Helical

Crosstalk Cancellation

MODULE 3

module 1 or 2 only)

= Helical Crosstalk Cancellation (Leave blank for

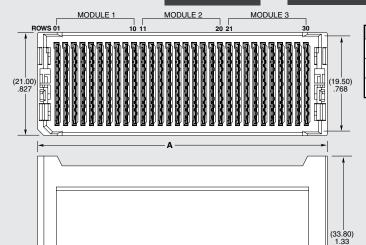
LEAD

PLATING OPTION

-35

= 35 mm

= 30 µ" (0.76 µm) Gold on contact area



= Helical

Crosstalk

Cancellation

(Leave blank for

module 1 only)

| MODULES | PAIRS | Α |
|---------|-------|------------------|
| 1 | 50 | (24.00) .945 |
| 2 | 100 | (41.50) 1.634 |
| 3 | 150 | (59.00) 2.323 |

